



PATENT

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Case Docket No. IIDAP10.001AUS

Date: November 6, 2002

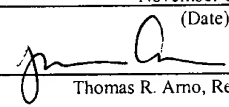
Page 1

Applicant : Miyoshi, Takashi)
App. No. : 09/844,155)
Filed : April 27, 2001)
For : COPPER ALLOY SUITABLE)
FOR AN IC LEAD PIN FOR)
A PIN GRID ARRAY)
PROVIDED ON A PLASTIC)
SUBSTRATE)
Examiner : Ip, Sikyin)
Art Unit : 1742)

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(Date)


Thomas R. Arno, Reg. No. 40,490

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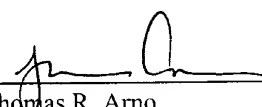
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Sir:

Transmitted herewith is an amendment in the above-identified application.

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Miyoshi, Takashi) Group Art Unit 1742
Appl. No. : 09/844,155)
Filed : April 27, 2001)
For : COPPER ALLOY SUITABLE FOR AN IC LEAD PIN FOR A PIN GRID ARRAY PROVIDED ON A PLASTIC SUBSTRATE)
Examiner : Ip, Sikyin)

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TC 1700

AMENDMENT AFTER FINAL

United States Patent and Trademark Office
P.O. Box 2327
Arlington, VA 22202

Dear Sir:

In response to the Office Action dated August 7, 2002, please amend the above captioned patent application as set forth below.

IN THE CLAIMS:

Please cancel Claim 7. Please amend Claims 1-4 as follows:

1. (Amended) A copper alloy suitable for an IC lead pin for a pin grid array provided on a plastic substrate, wherein the copper alloy is selected from the group consisting of:

a copper alloy consisting essentially of 0.05 to 0.5 wt% of Zn and 0.05 to 0.5 wt% of Mg, with the balance being made of unavoidable impurities and Cu;

a copper alloy consisting essentially of 0.1 to 1.0 wt% of Sn, with the balance being made of unavoidable impurities and Cu; and

a copper alloy consisting essentially of 0.1 to 1.0 wt% of Sn and 0.1 to 0.6 wt% of Ag, with the balance being made of unavoidable impurities and Cu;

wherein the copper alloy has conductivity of 50% IACS or more, and tensile stress of 400 MPa or more but 650 MPa or less.